LNJ8W0C83RA

Hight Bright Surface Mounting Chip LED

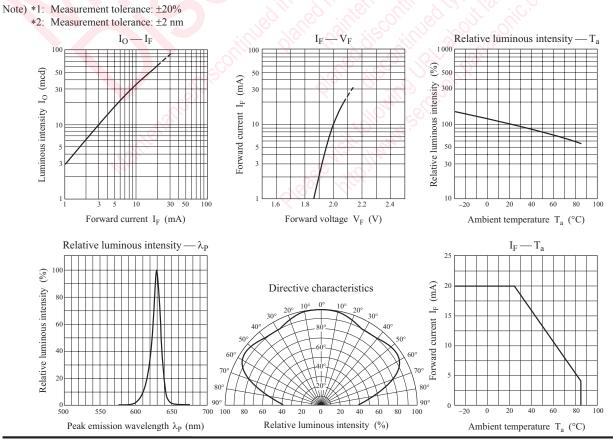
Wide Angle Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Absolute Maximum Ratings $I_a = 2$.	Lighting Colo			
Parameter	Symbol	Rating	Unit	• Orange
Power dissipation	PD	55	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	4	v	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	
Note) *: The condition of I_{FP} is duty 10%, Pulse	width 1 mse	ec.		
Electro-Optical Characteristics T _a =	= 25°C±3°	С		
			O I I I	

Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

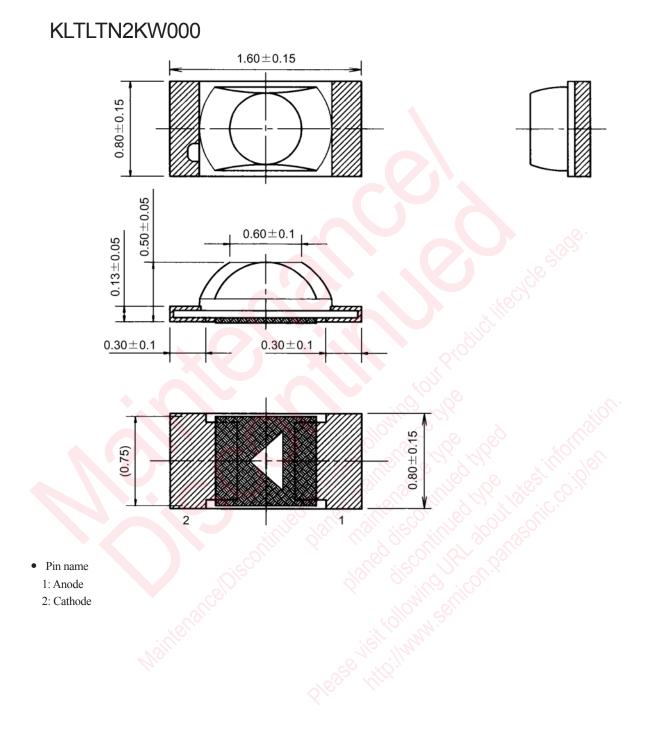
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	Io	$I_F = 5 \text{ mA}$	9.0	17.5		mcd
Reverse current	I _R	$V_R = 4 V$			100	μΑ
Forward voltage	V _F	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	λ_{P}	$I_F = 5 \text{ mA}$		630	ill'	nm
Dominant emission wavelength *2	λ_d	$I_F = 5 \text{ mA}$	615	620	627	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$	K	13	101	nm
Viewing angle	20 _{1/2}	$I_F = 5 \text{ mA}$	Se x	165	S,	0



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SHD00682BEK

Package (Unit: mm)



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